NCP6133

Advance Information
Dual Output 1/2/3 Phase +1/0 Phase Controller with Single SVID Interface for Desktop and Notebook CPU Applications

The NCP6133 dual output 1/2/3 phase plus 1/0 buck solution is optimized for Intel VR12 compatible CPUs. The controller combines true differential voltage sensing, differential inductor DCR current sensing, input voltage feed−forward, and adaptive voltage positioning to provide accurately regulated power for both Desktop and Notebook applications. The control system is based on Dual−Edge pulse−width modulation (PWM) combined with DCR current sensing providing the fastest initial response to dynamic load events and reduced system cost. It also sheds to single phase during light load operation and can auto frequency scale in light load while maintaining excellent transient performance.

Dual high performance operational error amplifiers are provided to simplify compensation of the system. Patented Dynamic Reference Injection further simplifies loop compensation by eliminating the need to compromise between closed−loop transient response and Dynamic VID performance. Patented Total Current Summing provides highly accurate current monitoring for droop and digital current monitoring.

ON Semiconductor®

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**QFN52
CASE 485BE**

MARKING DIAGRAM

NCP6133
AWLYYWWG

A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 28 of this data sheet.

Features
- Meets Intel VR12/IMVP7 Specifications
- Current Mode Dual Edge Modulation for Fastest Initial Response to Transient Loading
- Dual High Performance Operational Error Amplifier
- One Digital Soft Start Ramp for Both Rails
- Dynamic Reference Injection
- Accurate Total Summing Current Amplifier
- DAC with Droop Feed−forward Injection
- Dual High Impedance Differential Voltage and Total Current Sense Amplifiers
- Phase−to−Phase Dynamic Current Balancing
- "Lossless" DCR Current Sensing for Current Balancing
- Summed Thermally Compensated Inductor Current Sensing for Droop
- True Differential Current Balancing Sense Amplifiers for Each Phase
- Adaptive Voltage Positioning (AVP)

- Switching Frequency Range of 200 kHz – 1.0 MHz
- Startup into Pre−Charged Loads While Avoiding False OVP
- Power Saving Phase Shedding
- Vin Feed Forward Ramp Slope
- Pin Programming for Internal SVID Parameters
- Over Voltage Protection (OVP) and Under Voltage Protection (UVP)
- Over Current Protection (OCP)
- Dual Power Good Output with Internal Delays
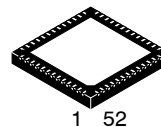- These Devices are Pb−Free and are RoHS Compliant

Applications
- Desktop & Notebook Processors
- Server Processors and Memory Power

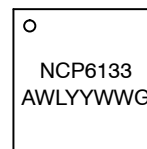This document contains information on a new product. Specifications and information herein are subject to change without notice.

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Publication Order Number:
NCP6133/D

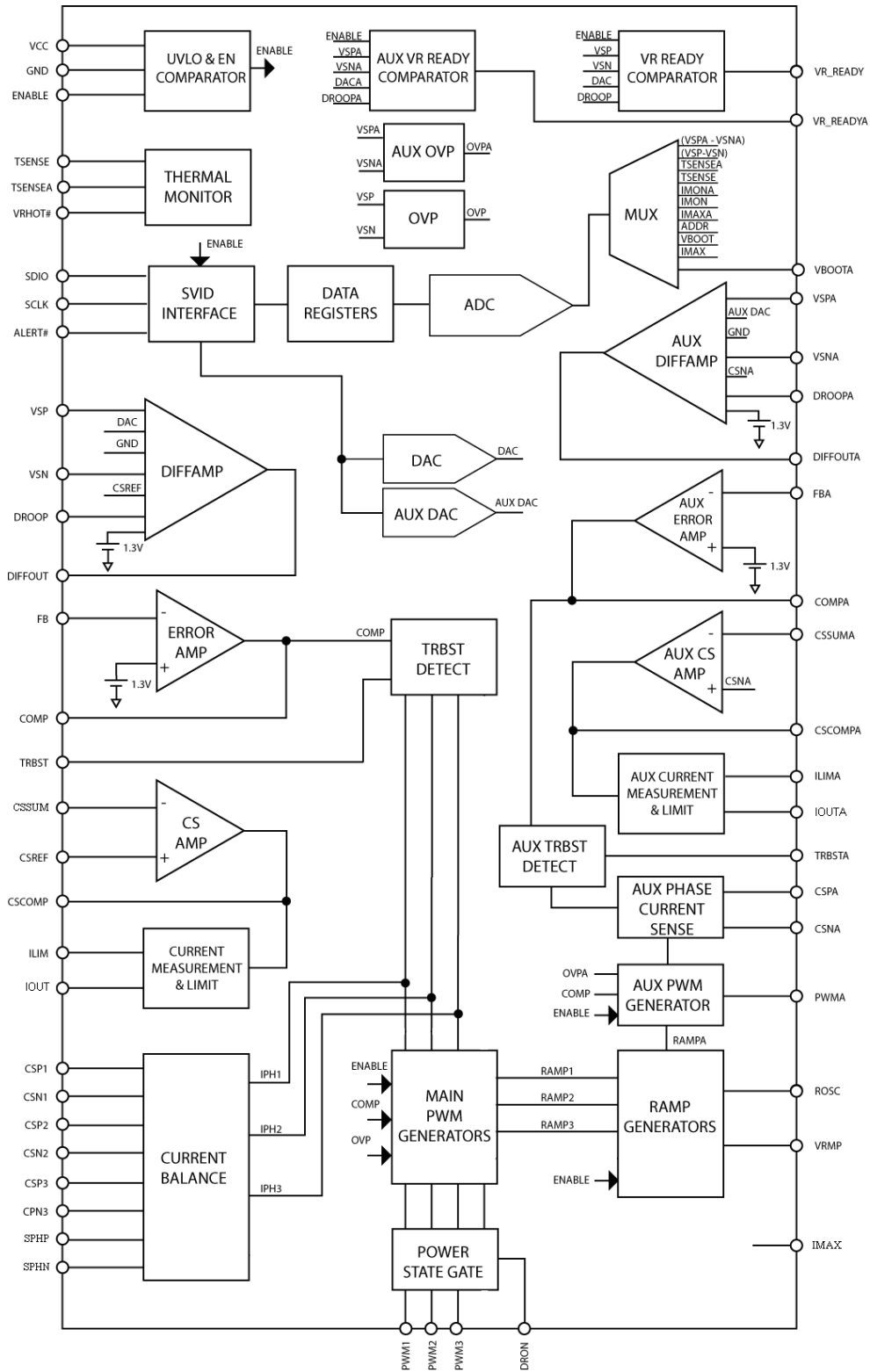# NCP6133

BLOCK DIAGRAM FOR NCP6133

Figure 1. Block Diagram

NCP6133

NCP6133 QFN52 SINGLE ROW PIN CONFIGURATIONS
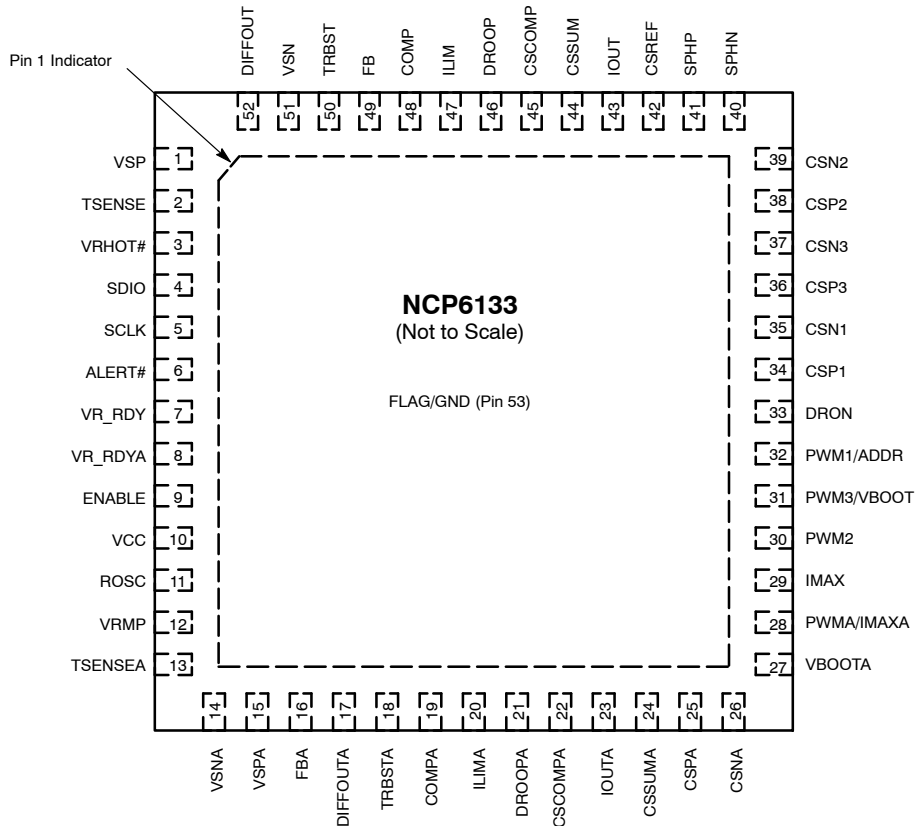
Figure 2. Pinout (Top View)

NCP6133 QFN52 SINGLE ROW PIN DESCRIPTIONS

Pin No.	Symbol	Description
1	VSP	Non−inverting input to the core differential remote sense amplifier.
2	TSENSE	Temp Sense input for the multiphase converter
3	VR_HOT#	Thermal logic output for over temperature.
4	SDIO	Serial VID data interface.
5	SCLK	Serial VID clock.
6	ALERT#	Serial VID ALERT#.
7	VR_RDY	Open drain output. High indicates that the core output is regulating.
8	VR_RDYA	Open drain output. High indicates that the aux output is regulating.
9	ENABLE	Logic input. Logic high enables both outputs and logic low disables both outputs.
10	VCC	Power for the internal control circuits. A decoupling capacitor is connected from this pin to ground.
11	ROSC	A resistance from this pin to ground programs the oscillator frequency. This pin supplies a trimmed output voltage of 2 V.
12	VRMP	Feed−forward input of Vin for the ramp slope compensation. The current fed into this pin is used to control the ramp of PWM slope
13	TSENSEA	Temp Sense input for the single phase converter
14	VSNA	Inverting input to the aux differential remote sense amplifier
15	VSPA	Non−inverting input to the aux differential remote sense amplifier

NCP6133 QFN52 SINGLE ROW PIN DESCRIPTIONS

Pin No.	Symbol	Description
16	FBA	Error amplifier voltage feedback for aux output
17	DIFFOUTA	Output of the aux differential remote sense amplifier
18	TRBSTA	Compensation pin for aux rail load transient boost.
19	COMPA	Output of the aux error amplifier and the inverting input of the PWM comparator for aux output
20	ILIMA	Over current shutdown threshold setting for aux output. A resistor to CSCOMPA sets the threshold.
21	DROOPA	Used to program droop function for aux output. It's connected to the resistor divider placed between CSCOMPA and CSREFA.
22	CSCOMPA	Output of total current sense amplifier for aux output
23	IOUTA	Total output current monitor for aux output
24	CSSUMA	Inverting input of total current sense amplifier for aux output
25	CSPA	Non–Inverting input to aux current sense amplifier
26	CSNA	Inverting input to aux current sense amplifier
27	VBOOTA	VBOOTA Voltage input pin. Set to adjust the aux boot–up voltage
28	PWMA / IMAXA	Aux PWM output to gate driver. Also as ICC_MAXA input pin for aux rail. During start up it is used to program ICC_MAXA with a resistor to ground
29	IMAX	ICC_MAX Input Pin for core rail. During start up it is used to program ICC_MAX with a resistor to ground
30	PWM2	Phase 2 PWM output only. Pull to V_{CC} will configure as 2–phase operation.
31	PWM3 / VBOOT	Phase 3 PWM output. Also as VBOOT input pin to adjust the core rail boot–up voltage. During start up it is used to program VBOOT with a resistor to ground.
32	PWM1 / ADDR	Phase 1 PWM output. Also as Address program pin. A resistor to ground on this pin programs the SVID address of the device.
33	DRON	Bidirectional gate drive enable for core output.
34	CSP1	Non–inverting input to current balance sense amplifier for phase 1
35	CSN1	Inverting input to current balance sense amplifier for phase 1
36	CSP3	Non–inverting input to current balance sense amplifier for phase 3
37	CSN3	Inverting input to current balance sense amplifier for phase 3
38	CSP2	Non–inverting input to current balance sense amplifier for phase 2
39	CSN2	Inverting input to current balance sense amplifier for phase 2
40	SPHN	Core rail single phase or multiphase selection, need to be tied to either VCC or ground
41	SPHP	Core rail single phase or multiphase selection, need to be tied to either VCC or ground
42	CSREF	Total output current sense amplifier reference voltage input.
43	IOUT	Total output current monitor for core output.
44	CSSUM	Inverting input of total current sense amplifier for core output.
45	CSCOMP	Output of total current sense amplifier for core output.
46	DROOP	Used to program droop function for core output. It's connected to the resistor divider placed between CSCOMP and CSREF summing node.
47	ILIM	Over current shutdown threshold setting for core output. Resistor to CSCOMP to set threshold.
48	COMP	Output of the error amplifier and the inverting inputs of the PWM comparators for the core output.
49	FB	Error amplifier voltage feedback for core output
50	TRBST	Compensation pin for core rail load transient boost.
51	VSN	Inverting input to the core differential remote sense amplifier.
52	DIFFOUT	Output of the core differential remote sense amplifier.
53	FLAG / GND	Power supply return (QFN Flag)

NCP6133 APPLICATION CONTROL CIRCUIT (TYPICAL)

Figure 3. NCP6133 VCCP and GT Regulator

ABSOLUTE MAXIMUM RATINGS

ELECTRICAL INFORMATION

Pin Symbol	V_{MAX}	V_{MIN}
COMP, COMPA	V_{CC} + 0.3 V	−0.3 V
CSCOMP, CSCOMPA	V_{CC} + 0.3 V	−0.3 V
VSN	GND + 300 mV	GND − 300 mV
DIFFOUT, DIFFOUTA	V_{CC} + 0.3 V	−0.3 V
VR_RDY, VR_RDYA	V_{CC} + 0.3 V	−0.3 V
VCC	6.5 V	−0.3 V
ROSC	V_{CC} + 0.3 V	−0.3 V
IOUT, IOUTA Output	2.0 V	−0.3 V
VRMP	+25 V	−0.3 V
All Other Pins	V_{CC} + 0.3 V	−0.3 V

*All signals referenced to GND unless noted otherwise.

THERMAL INFORMATION

Description	Symbol	Typ	Unit
Thermal Characteristic – QFN Package, (Note 1)	$R_{\theta JA}$	68	°C/W
Operating Junction Temperature Range, (Note 2)	T_J	−10 to 125	°C
Operating Ambient Temperature Range		−10 to 100	°C
Maximum Storage Temperature Range	T_{STG}	−40 to +150	°C
Moisture Sensitivity Level – QFN Package	MSL	1	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
*The maximum package power dissipation must be observed.
1. JESD 51−5 (1S2P Direct−Attach Method) with 0 LFM
2. JESD 51−7 (1S2P Direct−Attach Method) with 0 LFM

NCP6133 ELECTRICAL CHARACTERISTICS Unless otherwise stated: −10°C < T_A < 100°C; V_{CC} = 5 V; C_{VCC} = 0.1 μF

Parameter	Test Conditions	Min	Typ	Max	Unit
ERROR AMPLIFIER					
Input Bias Current	@ 1.3 V	−400		400	nA
Open Loop DC Gain	C_L = 20 pF to GND, R_L = 10 kΩ to GND		80		dB
Open Loop Unity Gain Bandwidth	C_L = 20 pF to GND, R_L = 10 kΩ to GND		50		MHz
Slew Rate	ΔV_{in} = 100 mV, G = 10 V/V, ΔV_{out} = 1.5 V − 2.5 V, C_L = 20 pF to GND, DC Load = 10 k to GND		20		V/μs
Maximum Output Voltage	I_{SOURCE} = 2.0 mA	3.5	–	–	V
Minimum Output Voltage	I_{SINK} = 2.0 mA	–	–	1	V
DIFFERENTIAL SUMMING AMPLIFIER					
Input Bias Current	VSP, VSPA ,VSN, VSNA = 1.3 V	−400	–	400	nA
VSP Input Voltage Range		−0.3	–	3.0	V
VSN Input Voltage Range		−0.3	–	0.3	V

3. Guaranteed by design or characterization data, not in production test.

NCP6133 ELECTRICAL CHARACTERISTICS Unless otherwise stated: $-10°C < T_A < 100°C$; $V_{CC} = 5$ V; $C_{VCC} = 0.1$ μF

Parameter	Test Conditions	Min	Typ	Max	Unit
DIFFERENTIAL SUMMING AMPLIFIER					
−3 dB Bandwidth	C_L = 20 pF to GND, R_L = 10 kΩ to GND		21		MHz
Closed Loop DC gain	VS+ to VS− = 0.5 to 1.3 V		1.0		V/V
Droop Accuracy	CSREF − DROOP = 80 mV DAC = 0.8 V to 1.2 V	−81.5		−78.5	mV
CURRENT SUMMING AMPLIFIER					
Offset Voltage (V_{os}) (Note 3)	$-10°C < T_A < 85°C$	−500		500	μV
Input Bias Current	CSSUM = CSSUMA = 1 V	−7.5		7.5	nA
Open Loop Gain			80		dB
Current Sense Unity Gain Bandwidth	C_L = 20 pF to GND, R_L = 10 kΩ to GND		10		MHz
Maximum CSCOMP (A) Output Voltage	I_{source} = 2 mA CSSUM(A) = CSCOMP(A)	3.5	–	–	V
Minimum CSCOMP(A) Output Voltage	I_{sink} = 2 mA CSSUM(A) = CSCOMP(A)	–	–	0.35	V
CURRENT BALANCE AMPLIFIER					
Input Bias Current	$CSP_{1-3} = CSN_{1-3} = 1.2$ V CSPA = CSNA = 1.2 V	−50	–	50	nA
Common Mode Input Voltage Range	CSPx = CSNx	0	–	2.0	V
Differential Mode Input Voltage Range	CSNx = 1.2 V	−100	–	100	mV
Input Offset Voltage Matching	CSPx = CSNx = 1.2 V, Measured from the average $-10°C < T_A < 85°C$	−1.5	–	1.5	mV
Current Sense Amplifier Gain	0 V < CSPx − CSNx < 0.1 V	5.6	6.0	6.4	V/V
Multiphase Current Sense Gain Matching	10 mV < CSNx = CSPx < 30 mV	−3		3	%
−3 dB Bandwidth			8		MHz
INPUT SUPPLY					
Supply Voltage Range		4.75		5.25	V
VCC Quiescent Current	EN = high		28	50	mA
	EN = low		0.01		mA
UVLO Threshold	V_{CC} rising			4.5	V
	V_{CC} falling	4.0			V
VCC UVLO Hysteresis		80	180		mV
DAC SLEW RATE					
Soft Start Slew Rate			2.5		mV/μs
Slew Rate Slow			5		mV/μs
Slew Rate Fast			10		mV/μs
AUX Soft Start Slew Rate			2.5		mV/μs
AUX Slew Rate Slow			2.5		mV/μs
AUX Slew Rate Fast			10		mV/μs
ENABLE INPUT					
Enable High Input Leakage Current	External 1 K pull−up to 3.3 V	–		1.0	μA
Upper Threshold	V_{UPPER}	0.8			V

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Parameter	Test Conditions	Min	Typ	Max	Unit
ENABLE INPUT					
Lower Threshold	V_{LOWER}			0.3	V
Total Hysteresis	$V_{UPPER} - V_{LOWER}$		90		mV
Enable Delay Time	Measure time from Enable transitioning HI to when DRON goes high, V_{boot} is not 0 V			5.0	ms
DRVON					
Output High Voltage	Sourcing 500 µA	3.0			V
Output Low Voltage	Sinking 500 µA			0.1	V
Input High Threshold		2.5			V
Input Low Threshold				1.5	V
Rise/Fall Time	C_L (PCB) = 20 pF, ΔV_o = 10% to 90%		10		ns
Internal Pull Down Resistance	EN = Low		70		kΩ
IOUT / IOUTA OUTPUT					
Input Referred Offset Voltage	I_{limit} to CSREF	−1.5		1.5	mV
Output Source Current	I_{limit} source current = 80 µA			820	µA
Current Gain	(IOUT$_{CURRENT}$)/ (ILIMIT$_{CURRENT}$), R_{ILIM} = 20 k, R_{IOUT} = 5.0 k, DAC = 0.8 V, 1.25 V, 1.52 V	9.5	10	10.5	
OSCILLATOR					
Switching Frequency Range		200	–	1000	kHz
3 Phase Operation	R_T = 6.98 kΩ	315	350	385	kHz
Rosc Output Voltage	R_T = 6.98 kΩ	1.95	2.00	2.05	V
OUTPUT OVER VOLTAGE AND UNDER VOLTAGE PROTECTION (OVP & UVP)					
Absolute Over Voltage Threshold During Soft Start	CSREF, CSNA	1.9	2.3		V
Over Voltage Threshold Above DAC	VSP(A) rising, DAC = 1.2 V and 1.52 V	170	300		mV
Over Voltage Delay	VSP(A) rising to PWMx low		40		ns
Under Voltage Threshold Below DAC	VSP(A) falling, (DAC = 1.2 V and 1.52 V)	250	300	350	mV
Under−voltage Delay			5		µs
VR12 DAC					
System Voltage Accuracy	1.0 V ≤ DAC < 1.52 V 0.8 V < DAC < 0.995 V 0.25 V < DAC < 0.795 V	−0.5 −5 −8		0.5 5 8	% mV mV
Droop Feed−Forward Up Current Droop Feed−Forward Down current	Measured on DROOP, DROOPA Measured on DROOP, DROOPA	55 19	65 25	72 31	µA
Droop Feed−Forward Pulse On−Time			0.16		µs
OVERCURRENT PROTECTION (Core Rail)					
ILIM Threshold Current (OCP shutdown after 50 µs delay)	(PS0) R_{lim} = 20k	9.0	10	11.0	µA
ILIM Threshold Current (immediate OCP shutdown)	(PS0) R_{lim} = 20k	13.5	15	16.5	µA
ILIM Threshold Current (OCP shutdown after 50 µs delay)	(PS1, PS2, PS3) R_{lim} = 20 k, N = number of phases in PS0 mode		10/N		µA

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Parameter	Test Conditions	Min	Typ	Max	Unit
OVERCURRENT PROTECTION (Core Rail)					
ILIM Threshold Current (immediate OCP shutdown)	(PS1, PS2, PS3) $R_{lim} = 20$ k, N = number of phases in PS0 mode		15/N		µA
Maximum Timer for OCP shutdown				55	µs
OVERCURRENT PROTECTION (+1 Rail)					
ILIM Threshold Current (OCP shutdown after 50 µs delay)	(PS0,1,2,3) $R_{lim} = 20$ k	9	10	11	µA
ILIM Threshold Current (immediate OCP shutdown)	(PS0,1,2,3) $R_{lim} = 20$ k	12.5	15	16.5	µA
Maximum Timer for OCP shutdown				55	µs
CSCOMP OCP Threshold		220			mV
VRMP (VIN Monitor)					
UVLO Threshold	VRMP falling	3.0	3.2	3.4	V
UVLO Hysteresis		600	800		mV
Leakage current	$V_{EN} = 0$ V, $V_{VRMP} = 26$ V			0.5	µA
MODULATORS (PWM COMPARATORS) FOR CORE AND AUX					
0% Duty Cycle	COMP voltage when the PWM outputs remain LO		1.3	–	V
100% Duty Cycle	COMP voltage when the PWM outputs remain HI $V_{RMP} = 12.0$ V	–	3.1	–	V
PWM Ramp Duty Cycle Matching	COMP = 2 V, PWM T_{on} matching		1		%
PWM Phase Angle Error	Between adjacent phases	–15		15	°
Ramp Feed−forward Voltage range		5		20	V
TRBST, TRBSTA					
TRBST/COMP offset	TRBST Starts Sinking Current		350		mV
TRBST Sink Capability			500		µA
TRBSTA/COMPA offset	TRBST Starts Sinking Current		350		mV
TRBSTA Sink Capability			500		µA
VR_HOT#					
Output Low Voltage	I_VRHOT = −4 mA			0.3	V
Output Leakage Current	High Impedance State	–1.0	–	1.0	µA
TSENSE/TSENSEA					
Alert# Assert Threshold			497		mV
Alert# De−assert Threshold			512		mV
VRHOT Assert Threshold			477		mV
VRHOT Rising Threshold			491		mV
TSENSE Bias Current		114	120	126	µA
ADC					
Voltage Range		0		2	V
Total Unadjusted Error (TUE)		–1		+1	%
Differential Nonlinearity (DNL)	8−bit			1	LSB
Power Supply Sensitivity			±1		%
Conversion Time			30		µs
Round Robin			90		µs

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NCP6133 ELECTRICAL CHARACTERISTICS Unless otherwise stated: −10°C < T_A < 100°C; V_{CC} = 5 V; C_{VCC} = 0.1 μF

Parameter	Test Conditions	Min	Typ	Max	Unit
VR_RDY, VR_RDYA (POWER GOOD) OUTPUT					
Output Low Saturation Voltage	$I_{VR\_RDY(A)}$ = 4 mA	–	–	0.3	V
Rise Time	External pull−up of 1 kΩ to 3.3 V, C_{TOT} = 45 pF, ΔVo = 10% to 90%	–	100		ns
Fall Time	External pull−up of 1 kΩ to 3.3 V, C_{TOT} = 45 pF, ΔVo = 90% to 10%		10		ns
Output Voltage at Power−up	VR_RDY, VR_RDYA pulled up to 5 V via 2 kΩ	–	–	1.0	V
Output Leakage Current When High	VR_RDY and VR_RDYA = 5.0 V	−1.0	–	1.0	μA
VR_RDY Delay (rising)	DAC = TARGET to VR_RDY		500		μs
VR_RDY Delay (falling)	From OCP or OVP	–	5	–	μs
PWM OUTPUTS					
Output High Voltage	Sourcing 500 μA	V_{CC} − 0.2 V	–	–	V
Output Mid Voltage	No Load, SetPS = 02	1.9	2.0	2.1	V
Output Low Voltage	Sinking 500 μA	–	–	0.7	V
Rise and Fall Time	CL (PCB) = 50 pF, ΔVo = GND to V_{CC}	–	10		ns
PWM Pin Source Current			100		μA
PWM Pin Threshold Voltage			3.3		V
Phase Detect Timer			20		μs
2/3 PHASE DETECTION					
PWM Pin Source Current			100		μA
PWM Pin Threshold Voltage			3.3		V
Phase Detect Timer			20		μs
IMAXA, ADDR, VBOOT INPUTS					
Sensing Current			10		μA
SPHP/SPHN (TO SELECT 1 PHASE MODE)					
V_{IL} (Note 3)	Input Low Voltage			0.5	V
V_{IH} (Note 3)	Input High Voltage	V_{CC} − 0.5			V
SCLK, SDIO, ALERT#					
V_{IL}	Input Low Voltage			0.4	V
V_{IH}	Input High Voltage	0.65			V
V_{OH}	Output High Voltage		1.05		V
Hysteresis Voltage		50			mV
R_{ON} (Note 3)	Buffer On Resistance (data line, ALERT#, and VRHOT)	4		13	Ω
Leakage Current	SDIO, SLCK, ALERT	−100		100	μA
Pad Capacitance (Note 3)				4.0	pF
VR clock to data delay (T_{co}) (Note 3)		4		8.3	ns
Setup time (T_{su}) (Note 3)		7			ns
Hold time (T_{hld}) (Note 3)		14			ns

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Table 1. VR12 VID CODES

VID7	VID6	VID5	VID4	VID3	VID2	VID1	VID0	Voltage (V)	HEX
0	0	0	0	0	0	0	0	OFF	00
0	0	0	0	0	0	0	1	0.25000	01
0	0	0	0	0	0	1	0	0.25500	02
0	0	0	0	0	0	1	1	0.26000	03
0	0	0	0	0	1	0	0	0.26500	04
0	0	0	0	0	1	0	1	0.27000	05
0	0	0	0	0	1	1	0	0.27500	06
0	0	0	0	0	1	1	1	0.28000	07
0	0	0	0	1	0	0	0	0.28500	08
0	0	0	0	1	0	0	1	0.29000	09
0	0	0	0	1	0	1	0	0.29500	0A
0	0	0	0	1	0	1	1	0.30000	0B
0	0	0	0	1	1	0	0	0.30500	0C
0	0	0	0	1	1	0	1	0.31000	0D
0	0	0	0	1	1	1	0	0.31500	0E
0	0	0	0	1	1	1	1	0.32000	0F
0	0	0	1	0	0	0	0	0.32500	10
0	0	0	1	0	0	0	1	0.33000	11
0	0	0	1	0	0	1	0	0.33500	12
0	0	0	1	0	0	1	1	0.34000	13
0	0	0	1	0	1	0	0	0.34500	14
0	0	0	1	0	1	0	1	0.35000	15
0	0	0	1	0	1	1	0	0.35500	16
0	0	0	1	0	1	1	1	0.36000	17
0	0	0	1	1	0	0	0	0.36500	18
0	0	0	1	1	0	0	1	0.37000	19
0	0	0	1	1	0	1	0	0.37500	1A
0	0	0	1	1	0	1	1	0.38000	1B
0	0	0	1	1	1	0	0	0.38500	1C
0	0	0	1	1	1	0	1	0.39000	1D
0	0	0	1	1	1	1	0	0.39500	1E
0	0	0	1	1	1	1	1	0.40000	1F
0	0	1	0	0	0	0	0	0.40500	20
0	0	1	0	0	0	0	1	0.41000	21
0	0	1	0	0	0	1	0	0.41500	22
0	0	1	0	0	0	1	1	0.42000	23
0	0	1	0	0	1	0	0	0.42500	24
0	0	1	0	0	1	0	1	0.43000	25
0	0	1	0	0	1	1	0	0.43500	26
0	0	1	0	0	1	1	1	0.44000	27
0	0	1	0	1	0	0	0	0.44500	28
0	0	1	0	1	0	0	1	0.45000	29
0	0	1	0	1	0	1	0	0.45500	2A

Table 1. VR12 VID CODES

VID7	VID6	VID5	VID4	VID3	VID2	VID1	VID0	Voltage (V)	HEX
0	0	1	0	1	0	1	1	0.46000	2B
0	0	1	0	1	1	0	0	0.46500	2C
0	0	1	0	1	1	0	1	0.47000	2D
0	0	1	0	1	1	1	0	0.47500	2E
0	0	1	0	1	1	1	1	0.48000	2F
0	0	1	1	0	0	0	0	0.48500	30
0	0	1	1	0	0	0	1	0.49000	31
0	0	1	1	0	0	1	0	0.49500	32
0	0	1	1	0	0	1	1	0.50000	33
0	0	1	1	0	1	0	0	0.50500	34
0	0	1	1	0	1	0	1	0.51000	35
0	0	1	1	0	1	1	0	0.51500	36
0	0	1	1	0	1	1	1	0.52000	37
0	0	1	1	1	0	0	0	0.52500	38
0	0	1	1	1	0	0	1	0.53000	39
0	0	1	1	1	0	1	0	0.53500	3A
0	0	1	1	1	0	1	1	0.54000	3B
0	0	1	1	1	1	0	0	0.54500	3C
0	0	1	1	1	1	0	1	0.55000	3D
0	0	1	1	1	1	1	0	0.55500	3E
0	0	1	1	1	1	1	1	0.56000	3F
0	1	0	0	0	0	0	0	0.56500	40
0	1	0	0	0	0	0	1	0.57000	41
0	1	0	0	0	0	1	0	0.57500	42
0	1	0	0	0	0	1	1	0.58000	43
0	1	0	0	0	1	0	0	0.58500	44
0	1	0	0	0	1	0	1	0.59000	45
0	1	0	0	0	1	1	0	0.59500	46
0	1	0	0	0	1	1	1	0.60000	47
0	1	0	0	1	0	0	0	0.60500	48
0	1	0	0	1	0	0	1	0.61000	49
0	1	0	0	1	0	1	0	0.61500	4A
0	1	0	0	1	0	1	1	0.62000	4B
0	1	0	0	1	1	0	0	0.62500	4C
0	1	0	0	1	1	0	1	0.63000	4D
0	1	0	0	1	1	1	0	0.63500	4E
0	1	0	0	1	1	1	1	0.64000	4F
0	1	0	1	0	0	0	0	0.64500	50
0	1	0	1	0	0	0	1	0.65000	51
0	1	0	1	0	0	1	0	0.65500	52
0	1	0	1	0	0	1	1	0.66000	53
0	1	0	1	0	1	0	0	0.66500	54
0	1	0	1	0	1	0	1	0.67000	55

Table 1. VR12 VID CODES

VID7	VID6	VID5	VID4	VID3	VID2	VID1	VID0	Voltage (V)	HEX
0	1	0	1	0	1	1	0	0.67500	56
0	1	0	1	0	1	1	1	0.68000	57
0	1	0	1	1	0	0	0	0.68500	58
0	1	0	1	1	0	0	1	0.69000	59
0	1	0	1	1	0	1	0	0.69500	5A
0	1	0	1	1	0	1	1	0.70000	5B
0	1	0	1	1	1	0	0	0.70500	5C
0	1	0	1	1	1	0	1	0.71000	5D
0	1	0	1	1	1	1	0	0.71500	5E
0	1	0	1	1	1	1	1	0.72000	5F
0	1	1	0	0	0	0	0	0.72500	60
0	1	1	0	0	0	0	1	0.73000	61
0	1	1	0	0	0	1	0	0.73500	62
0	1	1	0	0	0	1	1	0.74000	63
0	1	1	0	0	1	0	0	0.74500	64
0	1	1	0	0	1	0	1	0.75000	65
0	1	1	0	0	1	1	0	0.75500	66
0	1	1	0	0	1	1	1	0.76000	67
0	1	1	0	1	0	0	0	0.76500	68
0	1	1	0	1	0	0	1	0.77000	69
0	1	1	0	1	0	1	0	0.77500	6A
0	1	1	0	1	0	1	1	0.78000	6B
0	1	1	0	1	1	0	0	0.78500	6C
0	1	1	0	1	1	0	1	0.79000	6D
0	1	1	0	1	1	1	0	0.79500	6E
0	1	1	0	1	1	1	1	0.80000	6F
0	1	1	1	0	0	0	0	0.80500	70
0	1	1	1	0	0	0	1	0.81000	71
0	1	1	1	0	0	1	0	0.81500	72
0	1	1	1	0	0	1	1	0.82000	73
0	1	1	1	0	1	0	0	0.82500	74
0	1	1	1	0	1	0	1	0.83000	75
0	1	1	1	0	1	1	0	0.83500	76
0	1	1	1	0	1	1	1	0.84000	77
0	1	1	1	1	0	0	0	0.84500	78
0	1	1	1	1	0	0	1	0.85000	79
0	1	1	1	1	0	1	0	0.85500	7A
0	1	1	1	1	0	1	1	0.86000	7B
0	1	1	1	1	1	0	0	0.86500	7C
0	1	1	1	1	1	0	1	0.87000	7D
0	1	1	1	1	1	1	0	0.87500	7E
0	1	1	1	1	1	1	1	0.88000	7F
1	0	0	0	0	0	0	0	0.88500	80

Table 1. VR12 VID CODES

VID7	VID6	VID5	VID4	VID3	VID2	VID1	VID0	Voltage (V)	HEX
1	0	0	0	0	0	0	1	0.89000	81
1	0	0	0	0	0	1	0	0.89500	82
1	0	0	0	0	0	1	1	0.90000	83
1	0	0	0	0	1	0	0	0.90500	84
1	0	0	0	0	1	0	1	0.91000	85
1	0	0	0	0	1	1	0	0.91500	86
1	0	0	0	0	1	1	1	0.92000	87
1	0	0	0	1	0	0	0	0.92500	88
1	0	0	0	1	0	0	1	0.93000	89
1	0	0	0	1	0	1	0	0.93500	8A
1	0	0	0	1	0	1	1	0.94000	8B
1	0	0	0	1	1	0	0	0.94500	8C
1	0	0	0	1	1	0	1	0.95000	8D
1	0	0	0	1	1	1	0	0.95500	8E
1	0	0	0	1	1	1	1	0.96000	8F
1	0	0	1	0	0	0	0	0.96500	90
1	0	0	1	0	0	0	1	0.97000	91
1	0	0	1	0	0	1	0	0.97500	92
1	0	0	1	0	0	1	1	0.98000	93
1	0	0	1	0	1	0	0	0.98500	94
1	0	0	1	0	1	0	1	0.99000	95
1	0	0	1	0	1	1	0	0.99500	96
1	0	0	1	0	1	1	1	1.00000	97
1	0	0	1	1	0	0	0	1.00500	98
1	0	0	1	1	0	0	1	1.01000	99
1	0	0	1	1	0	1	0	1.01500	9A
1	0	0	1	1	0	1	1	1.02000	9B
1	0	0	1	1	1	0	0	1.02500	9C
1	0	0	1	1	1	0	1	1.03000	9D
1	0	0	1	1	1	1	0	1.03500	9E
1	0	0	1	1	1	1	1	1.04000	9F
1	0	1	0	0	0	0	0	1.04500	A0
1	0	1	0	0	0	0	1	1.05000	A1
1	0	1	0	0	0	1	0	1.05500	A2
1	0	1	0	0	0	1	1	1.06000	A3
1	0	1	0	0	1	0	0	1.06500	A4
1	0	1	0	0	1	0	1	1.07000	A5
1	0	1	0	0	1	1	0	1.07500	A6
1	0	1	0	0	1	1	1	1.08000	A7
1	0	1	0	1	0	0	0	1.08500	A8
1	0	1	0	1	0	0	1	1.09000	A9
1	0	1	0	1	0	1	0	1.09500	AA
1	0	1	0	1	0	1	1	1.10000	AB

Table 1. VR12 VID CODES

VID7	VID6	VID5	VID4	VID3	VID2	VID1	VID0	Voltage (V)	HEX
1	0	1	0	1	1	0	0	1.10500	AC
1	0	1	0	1	1	0	1	1.11000	AD
1	0	1	0	1	1	1	0	1.11500	AE
1	0	1	0	1	1	1	1	1.12000	AF
1	0	1	1	0	0	0	0	1.12500	B0
1	0	1	1	0	0	0	1	1.13000	B1
1	0	1	1	0	0	1	0	1.13500	B2
1	0	1	1	0	0	1	1	1.14000	B3
1	0	1	1	0	1	0	0	1.14500	B4
1	0	1	1	0	1	0	1	1.15000	B5
1	0	1	1	0	1	1	0	1.15500	B6
1	0	1	1	0	1	1	1	1.16000	B7
1	0	1	1	1	0	0	0	1.16500	B8
1	0	1	1	1	0	0	1	1.17000	B9
1	0	1	1	1	0	1	0	1.17500	BA
1	0	1	1	1	0	1	1	1.18000	BB
1	0	1	1	1	1	0	0	1.18500	BC
1	0	1	1	1	1	0	1	1.19000	BD
1	0	1	1	1	1	1	0	1.19500	BE
1	0	1	1	1	1	1	1	1.20000	BF
1	1	0	0	0	0	0	0	1.20500	C0
1	1	0	0	0	0	0	1	1.21000	C1
1	1	0	0	0	0	1	0	1.21500	C2
1	1	0	0	0	0	1	1	1.22000	C3
1	1	0	0	0	1	0	0	1.22500	C4
1	1	0	0	0	1	0	1	1.23000	C5
1	1	0	0	0	1	1	0	1.23500	C6
1	1	0	0	0	1	1	1	1.24000	C7
1	1	0	0	1	0	0	0	1.24500	C8
1	1	0	0	1	0	0	1	1.25000	C9
1	1	0	0	1	0	1	0	1.25500	CA
1	1	0	0	1	0	1	1	1.26000	CB
1	1	0	0	1	1	0	0	1.26500	CC
1	1	0	0	1	1	0	1	1.27000	CD
1	1	0	0	1	1	1	0	1.27500	CE
1	1	0	0	1	1	1	1	1.28000	CF
1	1	0	1	0	0	0	0	1.28500	D0
1	1	0	1	0	0	0	1	1.29000	D1
1	1	0	1	0	0	1	0	1.29500	D2
1	1	0	1	0	0	1	1	1.30000	D3
1	1	0	1	0	1	0	0	1.30500	D4
1	1	0	1	0	1	0	1	1.31000	D5
1	1	0	1	0	1	1	0	1.31500	D6

Table 1. VR12 VID CODES

VID7	VID6	VID5	VID4	VID3	VID2	VID1	VID0	Voltage (V)	HEX
1	1	0	1	0	1	1	1	1.32000	D7
1	1	0	1	1	0	0	0	1.32500	D8
1	1	0	1	1	0	0	1	1.33000	D9
1	1	0	1	1	0	1	0	1.33500	DA
1	1	0	1	1	0	1	1	1.34000	DB
1	1	0	1	1	1	0	0	1.34500	DC
1	1	0	1	1	1	0	1	1.35000	DD
1	1	0	1	1	1	1	0	1.35500	DE
1	1	0	1	1	1	1	1	1.36000	DF
1	1	1	0	0	0	0	0	1.36500	E0
1	1	1	0	0	0	0	1	1.37000	E1
1	1	1	0	0	0	1	0	1.37500	E2
1	1	1	0	0	0	1	1	1.38000	E3
1	1	1	0	0	1	0	0	1.38500	E4
1	1	1	0	0	1	0	1	1.39000	E5
1	1	1	0	0	1	1	0	1.39500	E6
1	1	1	0	0	1	1	1	1.40000	E7
1	1	1	0	1	0	0	0	1.40500	E8
1	1	1	0	1	0	0	1	1.41000	E9
1	1	1	0	1	0	1	0	1.41500	EA
1	1	1	0	1	0	1	1	1.42000	EB
1	1	1	0	1	1	0	0	1.42500	EC
1	1	1	0	1	1	0	1	1.43000	ED
1	1	1	0	1	1	1	0	1.43500	EE
1	1	1	0	1	1	1	1	1.44000	EF
1	1	1	1	0	0	0	0	1.44500	F0
1	1	1	1	0	0	0	1	1.45000	F1
1	1	1	1	0	0	1	0	1.45500	F2
1	1	1	1	0	0	1	1	1.46000	F3
1	1	1	1	0	1	0	0	1.46500	F4
1	1	1	1	0	1	0	1	1.47000	F5
1	1	1	1	0	1	1	0	1.47500	F6
1	1	1	1	0	1	1	1	1.48000	F7
1	1	1	1	1	0	0	0	1.48500	F8
1	1	1	1	1	0	0	1	1.49000	F9
1	1	1	1	1	0	1	0	1.49500	FA
1	1	1	1	1	0	1	1	1.50000	FB
1	1	1	1	1	1	0	0	1.50500	FC
1	1	1	1	1	1	0	1	1.51000	FD
1	1	1	1	1	1	1	0	1.51500	FE
1	1	1	1	1	1	1	1	1.52000	FF

NCP6133
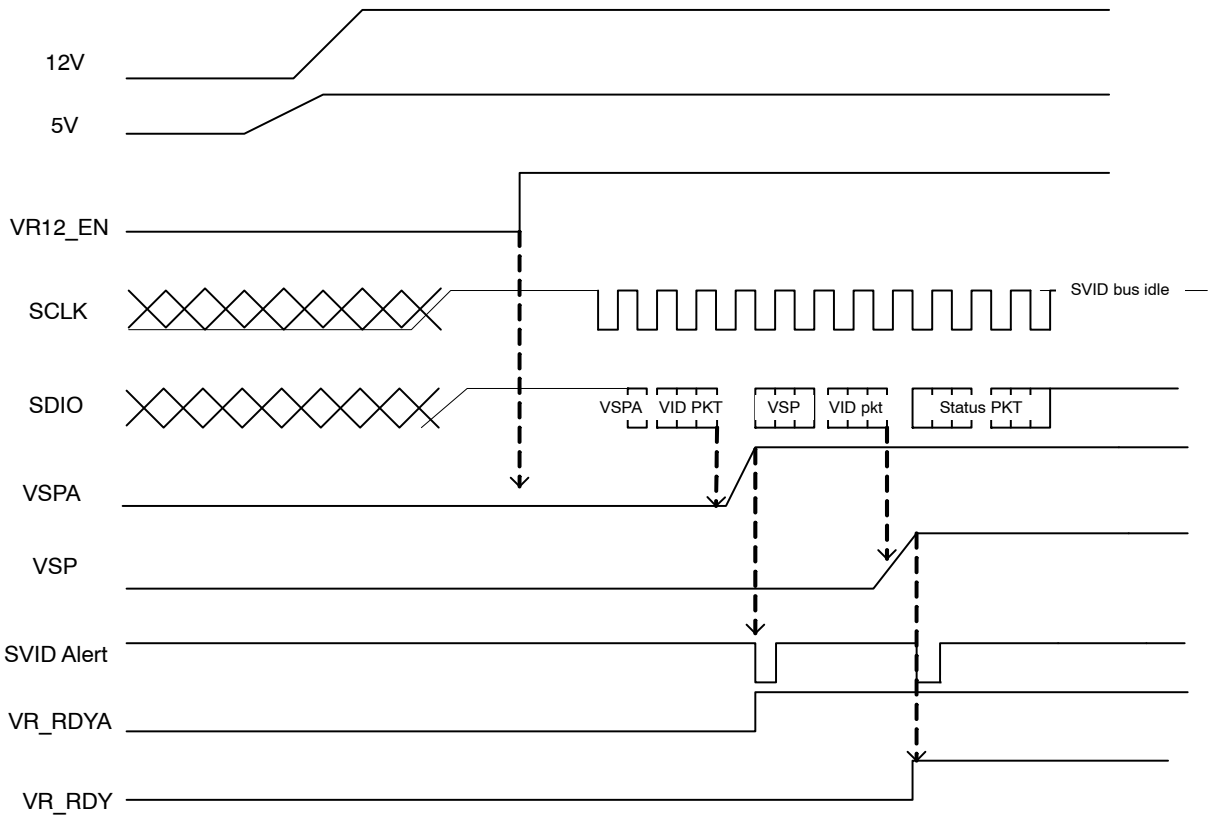
Figure 4. Start Up Timing Diagram

CPU Driving, Single Data Rate

T_{co_CPU} = clock to data delay in CPU
$t_{su} = 0.5 * T − T_{co\_CPU}$
$t_{hld} = 0.5 * T + T_{co\_CPU}$

VR Driving, Single Data Rate

T_{co_vr} = clock to data delay in vr
$t_{su} = T − 2 * T_{fly} − T_{co\_VR}$
$t_{hld} = 2 * T_{fly} + T_{co\_VR}$
T_{fly} propagation time on Serial VID bus
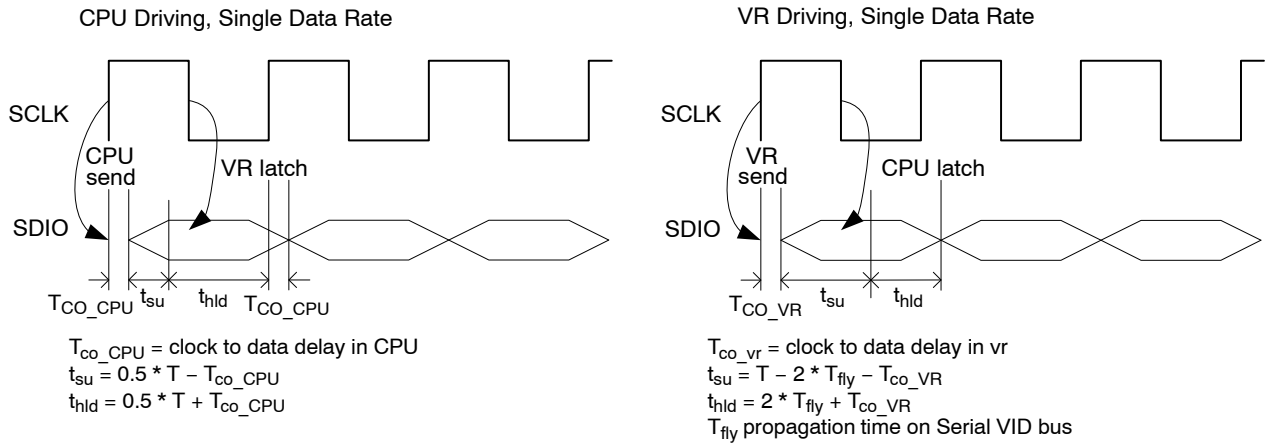
Figure 5. SVID Timing Diagram

Table 2. STATE TRUTH TABLE

STATE	VR_RDY(A) Pin	Error AMP Comp(A) Pin	OVP(A) and UVP(A)	DRVON Pin	Method of Reset
POR $0 < V_{CC} < UVLO$	N/A	N/A	N/A	Resistive pull down	
Disabled EN < threshold UVLO > threshold	Low	Low	Disabled	Low	
Start up Delay & Calibration EN > threshold UVLO > threshold	Low	Low	Disabled	Low	
DRVON Fault EN > threshold UVLO > threshold DRVON < threshold	Low	Low	Disabled	Resistive pull up	Driver must release DRVON to high
Soft Start EN > threshold UVLO > threshold DRVON > High	Low	Operational	Active / No latch	High	
Normal Operation EN > threshold UVLO > threshold DRVON > High	High	Operational	Active / Latching	High	N/A
Over Voltage	Low	N/A	DAC + 150 mV	High	
Over Current	Low	Operational	Last DAC Code	Low	
VID Code = 00h	Low: if Reg34h:bit0 = 0; High: if Reg34h:bit0 = 1	Clamped to 0.9 V	Disabled	High, PWM outputs in low state	
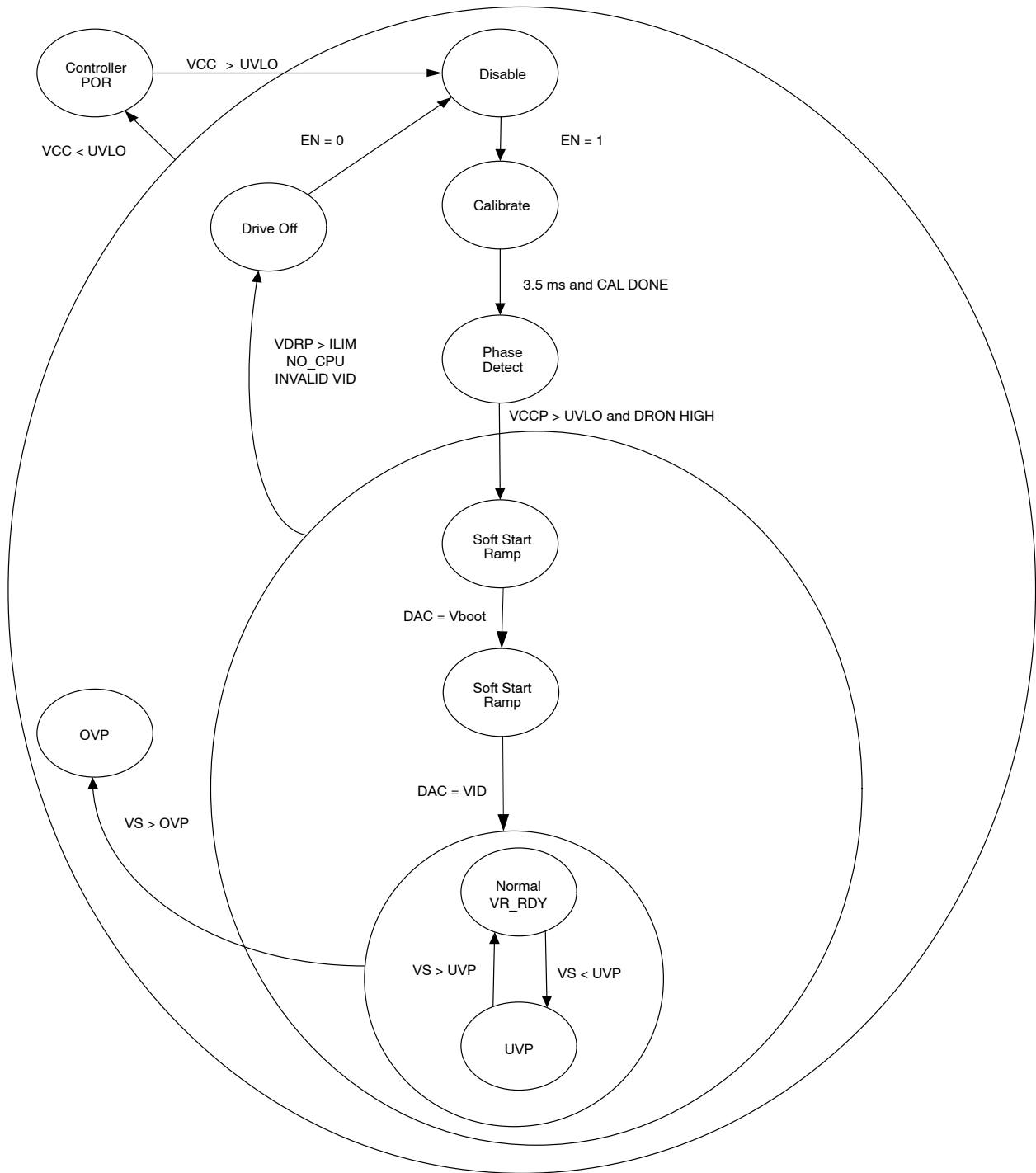
Figure 6. State Diagram

NCP6133

General

The NCP6133 is a dual output one/two/three phases plus one phase dual edge modulated multiphase PWM controller designed to meet the Intel VR12 specifications with a serial SVID control interface. The NCP6133 implements PS0, PS1, PS2 and PS3 power saving states. It is designed to work in notebook, desktop, and server applications.

For Core Rail:

Power Status	PWM Output Operating Mode
PS0	Multi–phase PWM interleaving output
PS1	Single–phase COT CCM mode (PWM1 only, PWM2~3 stay in Mid)
PS2	Single–phase COT DCM mode (PWM1 only, PWM2~3 stay in Mid)
PS3	Single–phase COT DCM mode (PWM1 only, PWM2~3 stay in Mid)

For AUX Rail:

Power Status	PWM Output Operating Mode
PS0	PWM interleaving with Core Rail / COT CCM mode
PS1	PWM interleaving with Core Rail / COT CCM mode
PS2	Single–phase COT DCM mode
PS3	Single–phase COT DCM mode

VID code change is supported by SVID interface with three options as below:

Option	SVID Command Code	Feature	Register Address (Indicating the slew rate of VID code change)
SetVID_Fast	01h	> 10 mV/μs VID code change slew rate	24h
SetVID_Slow	02h	= 1/4 of SetVID_Fast VID code change slew rate	25h
SetVID_Decay	03h	No control, VID code down	N/A

Serial VID

The NCP6133 supports the Intel serial VID interface. It communicates with the microprocessor through three wires (SCLK, SDIO, ALERT#). The table of supported registers is shown below.

Index	Name	Description	Access	Default
00h	Vendor ID	Uniquely identifies the VR vendor. The vendor ID assigned by Intel to ON Semiconductor is 0x1Ah	R	0x1Ah
01h	Product ID	Uniquely identifies the VR product. The VR vendor assigns this number.	R	0x51
02h	Product Revision	Uniquely identifies the revision or stepping of the VR control IC. The VR vendor assigns this data.	R	0x0A
05h	Protocol ID	Identifies the SVID Protocol the controller supports	R	0x01
06h	Capability	Informs the Master of the controller's Capabilities, 1 = supported, 0 = not supported Bit 7 = Iout_format. Bit 7 = 0 when 1A = 1LSB of Reg 15h. Bit 7 = 1 when Reg 15 FFh = Icc_Max. Default = 1 Bit 6 = ADC Measurement of Temp Supported = 1 Bit 5 = ADC Measurement of Pin Supported = 0 Bit 4 = ADC Measurement of Vin Supported = 0 Bit 3 = ADC Measurement of Iin Supported = 0 Bit 2 = ADC Measurement of Pout Supported = 1 Bit 1 = ADC Measurement of Vout Supported = 1 Bit 0 = ADC Measurement of Iout Supported = 1	R	0xC7
07h	Generic ID	51h or 31h, depending on the generic	R	51h or 31h
10h	Status_1	Data register read after the ALERT# signal is asserted. Conveying the status of the VR.	R	00h

Index	Name	Description	Access	Default
11h	Status_2	Data register showing optional status_2 data.	R	00h
12h	Temp zone	Data register showing temperature zones the system is operating in	R	00h
15h	I_out	8 bit binary word ADC of current. This register reads 0xFF when the output current is at Icc_Max	R	01h
16h	V_out	8 bit binary word ADC of output voltage, measured between VSP and VSN. LSB size is 8 mV	R	01h
17h	VR_Temp	8 bit binary word ADC of voltage. Binary format in deg C, IE 100C = 64h. A value of 00h indicates this function is not supported	R	01h
18h	P_out	8 bit binary word representative of output power. The output voltage is multiplied by the output current value and the result is stored in this register. A value of 00h indicates this function is not supported	R	01h
1Ch	Status 2 Last read	When the status 2 register is read its contents are copied into this register. The format is the same as the Status 2 Register.	R	00h
21h	Icc_Max	Data register containing the Icc_Max the platform supports. The value is measured on the ICCMAX pin on power up and placed in this register. From that point on the register is read only.	R	00h
22h	Temp_Max	Data register containing the max temperature the platform supports and the level VR_hot asserts. This value defaults to 100°C and programmable over the SVID Interface	R/W	64h
24h	SR_fast	Slew Rate for SetVID_fast commands. Binary format in mV/μs.	R	0Ah
25h	SR_slow	Slew Rate for SetVID_slow commands. It is 4X slower than the SR_fast rate. Binary format in mV/μs	R	02h
26h	Vboot	The Vboot is programmed using resistors on the Vboot pin which is sensed on power up. The controller will ramp to Vboot and hold at Vboot until it receives a new SVID SetVID command to move to a different voltage.	R	00h
30h	Vout_Max	Programmed by master and sets the maximum VID the VR will support. If a higher VID code is received, the VR should respond with "not supported" acknowledge. VR 12 VID format.	RW	FBh
31h	VID setting	Data register containing currently programmed VID voltage. VID data format.	RW	00h
32h	Pwr State	Register containing the current programmed power state.	RW	00h

33h	Offset	Sets offset in VID steps added to the VID setting for voltage margining. Bit 7 is sign bit, 0 = positive margin, 1= negative margin. Remaining 7 BITS are # VID steps for margin 2s complement.
		00h = no margin
		01h = +1 VID step
		02h = +2 VID steps
		FFh = −1 VID step
		FEh = −2 VID steps.
			RW	00h

34h	MultiVR Config			

Boot Voltage Programming

The NCP6133 has a Vboot voltage register that can be externally programmed for each output. The VBOOTA also provides a feature that allows the "+1" single phase output to be disabled and effectively removed from the SVID bus. If the single phase output is disabled it alters the SVID address setting table to allow the multi−phase rail to show up at an even or odd address. See the Boot Voltage Table below.

Table 3. BOOT VOLTAGE TABLE

Boot Voltage (V)	Resistor Value (Ω)
0	10k
0.9	25k
1.0	45k
1.1	70k
1.2	95k
1.35	125k
1.5	165k
Shutdown (VBOOTA only)	VBOOTA = VCC

Addressing Programming

The NCP6133 supports seven possible dual SVID device addresses and eight possible single device addresses. Pin 32 (PWM1/ADDR) is used to set the SVID address. On power up a 10 μA current is sourced from this pin through a resistor connected to this pin and the resulting voltage is measured. The two tables below provide the resistor values for each corresponding SVID address. For dual addressing follow the Dual SVID Address Table. The address value is latched at startup. If VBOOTA is pulled to V_{CC} the aux rail will be removed from the SVID bus, the address will then follow the Single Address SVID table below.

Table 4. DUAL SVID ADDRESS TABLE

Resistor Value	Main Rail SVID Address	Aux Rail SVID Address
10k	0000	0001
25k	0010	0011
45k	0100	0101
70k	0110	0111
95k	1000	1001
125k	1010	1011
165k	1100	1101

Table 5. SINGLE SVID ADDRESS TABLE

Resistor Value	Main Rail SVID Address (VBOOTA tied to VCC)
10k	0000
22k	0001
36k	0010
51k	0011
68k	0100
91k	0101
120k	0110
160k	0111
220k	1000

Remote Sense Amplifier

A high performance high input impedance true differential amplifier is provided to accurately sense the output voltage of the regulator. The VSP and VSN inputs should be connected to the regulator's output voltage sense points. The remote sense amplifier takes the difference of the output voltage with the DAC voltage and adds the droop voltage to DIFFOUT.

$$V_{DIFFOUT} = \left(V_{VSP} - V_{VSN}\right) + \left(1.3\ V - V_{DAC}\right) + \left(V_{DROOP} - V_{CSREF}\right) \quad \text{(eq. 1)}$$

This signal then goes through a standard error compensation network and into the inverting input of the error amplifier. The non−inverting input of the error amplifier is connected to the same 1.3 V reference used for the differential sense amplifier output bias.

High Performance Voltage Error Amplifier

A high performance error amplifier is provided for high bandwidth transient performance. A standard type 3 compensation circuit is normally used to compensate the system.

Differential Current Feedback Amplifiers

Each phase has a low offset differential amplifier to sense that phase current for current balance and per phase OCP protection during soft−start. The inputs to the CSNx and CSPx pins are high impedance inputs. It is recommended that any external filter resistor RCSN does not exceed 10 kΩ to avoid offset issues with leakage current. It is also recommended that the voltage sense element be no less than 0.5 mΩ for accurate current balance. Fine tuning of this time constant is generally not required.
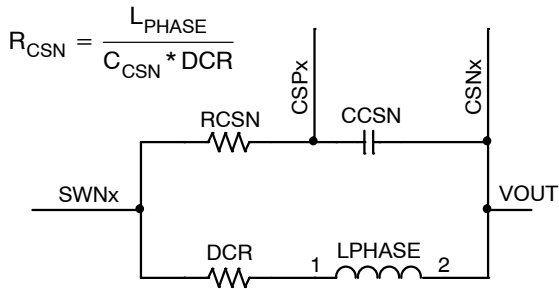
$$R_{CSN} = \frac{L_{PHASE}}{C_{CSN} * DCR}$$

Figure 7.

The individual phase current is summed into the PWM comparator feedback. In this way current is balanced via a current mode control approach.

Total Current Sense Amplifier

The NCP6133 uses a patented approach to sum the phase currents into a single temperature compensated total current signal. This signal is then used to generate the output voltage droop, total current limit, and the output current monitoring functions. The total current signal is floating with respect to CSREF. The current signal is the difference between CSCOMP and CSREF. The Ref(n) resistors sum the signals from the output side of the inductors to create a low impedance virtual ground. The amplifier actively filters and gains up the voltage applied across the inductors to recover the voltage drop across the inductor series resistance (DCR). Rth is placed near an inductor to sense the temperature of the inductor. This allows the filter time constant and gain to be a function of the Rth NTC resistor and compensate for the change in the DCR with temperature.
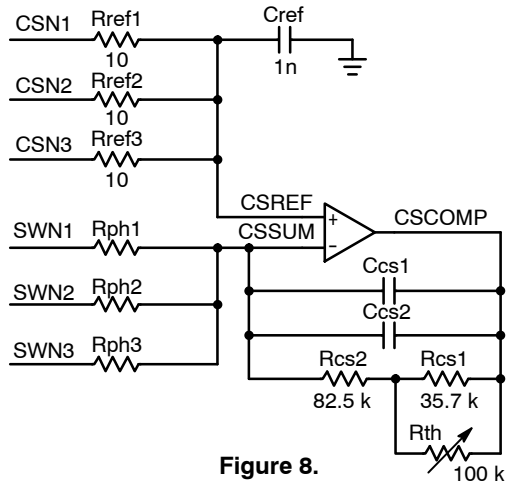
Figure 8.

The DC gain equation for the current sensing:

$$V_{CSCOMP-CSREF} = -\frac{Rcs2 + \frac{Rcs1*Rth}{Rcs1 + Rth}}{Rph} * \left(Iout_{Total} * DCR\right) \quad \text{(eq. 2)}$$

Set the gain by adjusting the value of the Rph resistors. The DC gain should set to the output voltage droop. If the voltage from CSCOMP to CSREF is less than 100 mV at

ICCMAX then it is recommended to increase the gain of the CSCOMP amp and add a resister divider to the Droop pin filter. This is required to provide a good current signal to offset voltage ratio for the ILIMIT pin. When no droop is needed, the gain of the amplifier should be set to provide ~100 mV across the current limit programming resistor at full load. The values of Rcs1 and Rcs2 are set based on the 100k NTC and the temperature effect of the inductor and should not need to be changed. The NTC should be placed near the closest inductor. The output voltage droop should be set with the droop filter divider.

The pole frequency in the CSCOMP filter should be set equal to the zero from the output inductor. This allows the circuit to recover the inductor DCR voltage drop current signal. Ccs1 and Ccs2 are in parallel to allow for fine tuning of the time constant using commonly available values. It is best to fine tune this filter during transient testing.

$$F_Z = \frac{DCR @ 25°C}{2 * PI * L_{Phase}} \quad \text{(eq. 3)}$$

$$F_P = \frac{1}{2 * PI * \left(Rcs2 + \frac{Rcs1*Rth@25°C}{Rcs1 + Rth@25°C}\right) * (Ccs1 + Ccs2)} \quad \text{(eq. 4)}$$

Programming the Current Limit

The current limit thresholds are programmed with a resistor between the ILIMIT and CSCOMP pins. The ILIMIT pin mirrors the voltage at the CSREF pin and mirrors the sink current internally to IOUT (reduced by the I_{OUT} Current Gain) and the current limit comparators. The 100% current limit trips if the ILIMIT sink current exceeds 10 μA for 50 μs. The 150% current limit trips with minimal delay if the ILIMIT sink current exceeds 15 μA. Set the value of the current limit resistor based on the CSCOMP − CSREF voltage as shown below.

$$R_{LIMIT} = \frac{\frac{Rcs2 + \frac{Rcs1*Rth}{Rcs1 + Rth}}{Rph} * \left(Iout_{LIMIT} * DCR\right)}{10\mu} \quad \text{(eq. 5)}$$

or

$$R_{LIMIT} = \frac{V_{CSCOMP-CSREF@ILIMIT}}{10\mu} \quad \text{(eq. 6)}$$

Programming DROOP and DAC Feed−Forward Filter

The signals DROOP and CSREF are differentially summed with the output voltage feedback to add precision voltage droop to the output voltage. The total current feedback should be filtered before it is applied to the DROOP pin. This filter impedance provides DAC feed−forward during dynamic VID changes. Programming this filter can be made simpler if CSCOMP−CSREF is equal to the droop voltage. R_{droop} sets the gain of the DAC feed−forward and C_{droop} provides the time constant to cancel the time constant of the system per the following equations. C_{out} is the total output capacitance and Rout is the output impedance of the system.
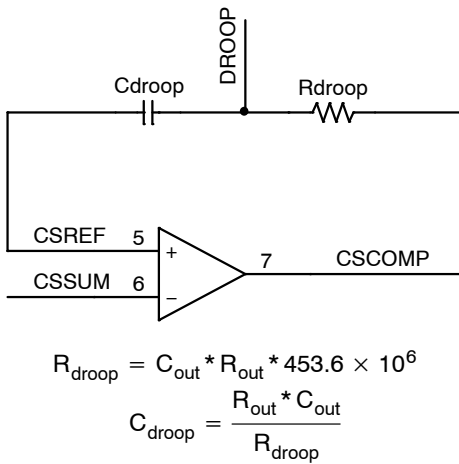
Figure 9.

$$R_{droop} = C_{out} * R_{out} * 453.6 \times 10^6$$

$$C_{droop} = \frac{R_{out} * C_{out}}{R_{droop}}$$

If the Droop at maximum load is less than 100 mV at ICCMAX we recommend altering this filter into a voltage divider such that a larger signal can be provided to the ILIMIT resistor by increasing the CSCOMP amp gain for better current monitor accuracy. The DROOP pin divider gain should be set to provide a voltage from DROOP to CSREF equal to the amount of voltage droop desired in the output. A current is applied to the DROOP pin during dynamic VID. In this case Rdroop1 in parallel with Rdroop2 should be equal to R_{droop}.
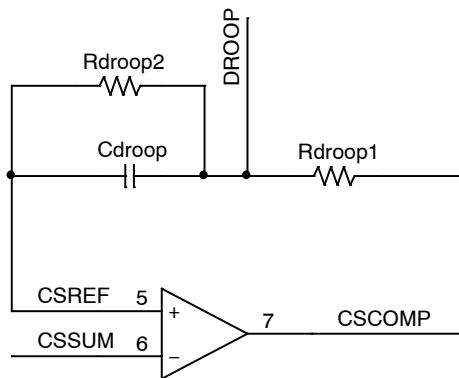
Figure 10.

Programming IOUT

The IOUT pin sources a current in proportion to the ILIMIT sink current. The voltage on the IOUT pin is monitored by the internal A/D converter and should be scaled with an external resistor to ground such that a load equal to ICCMAX generates a 2 V signal on IOUT. A pull−up resistor from 5 V V_{CC} can be used to offset the I_{OUT} signal positively if needed.

$$R_{IOUT} = \frac{2.0 \text{ V} * R_{LIMIT}}{10 * \frac{Rcs2 + \frac{Rcs1*Rth}{Rcs1 + Rth}}{Rph} * \left(Iout_{ICC\_MAX} * DCR\right)} \quad \text{(eq. 7)}$$

Programming ICC_MAX and ICC_MAXA

The SVID interface provides the platform ICC_MAX value at register 21h for both the multiphase and the single phase rail. A resistor to ground on the IMAX and IMAXA pins program these registers at the time the part is enabled. 10 μA is sourced from these pins to generate a voltage on the program resistor. The value of the register is 1 A per LSB and is set by the equation below. The resistor value should be no less than 10 k.

$$ICC\_MAX_{21h} = \frac{R * 10 \text{ μA} * 256 \text{ A}}{2 \text{ V}} \quad \text{(eq. 8)}$$

Programming TSENSE and TSENSEA

Two temperature sense inputs are provided. A precision current is sourced out the output of the TSENSE and TSENSEA pins to generate a voltage on the temperature sense network. The voltages on the temperature sense inputs are sampled by the internal A/D converter. A 100 k NTC similar to the VISHAY ERT−J1VS104JA should be used. Rcomp1 is mainly used for noise. See the specification table for the thermal sensing voltage thresholds and source current.
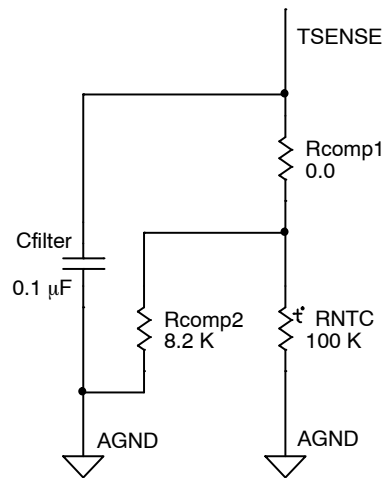

Figure 11.

Precision Oscillator

A programmable precision oscillator is provided. The clock oscillator serves as the master clock to the ramp generator circuit. This oscillator is programmed by a resistor to ground on the ROSC pin. The oscillator frequency range is between 200 kHz/phase to 1 MHz/phase. The ROSC pin provides approximately 2 V out and the source current is mirrored into the internal ramp oscillator. The oscillator frequency is approximately proportional to the current flowing in the ROSC resistor.

NCP6133 Operating Frequency versus R_{osc}:

$$\frac{10.5 \text{ k}\Omega \times 350 \text{ kHz}}{Fs} = R_{OSC} \quad \text{(eq. 9)}$$

The oscillator generates triangle ramps that are 0.5 ~ 2.5 V in amplitude depending on the VRMP pin voltage to provide input voltage feed forward compensation. The ramps are equally spaced out of phase with respect to each other and the signal phase rail is set half way between phases 1 and 2 of the multi phase rail for minimum input ripple current.

Programming the Ramp Feed−Forward Circuit

The ramp generator circuit provides the ramp used by the PWM comparators. The ramp generator provides voltage feed−forward control by varying the ramp magnitude with respect to the VRMP pin voltage. The VRMP pin also has a 4 V UVLO function. The VRMP UVLO is only active after the controller is enabled. The VRMP pin is high impedance input when the controller is disabled.

The PWM ramp time is changed according to the following,

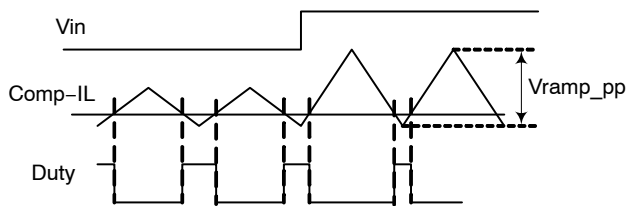$$V_{RAMPpk-pk_{PP}} = 0.1 * V_{VRMP} \qquad \text{(eq. 10)}$$

Figure 12.

Programming TRBST

The TRBST pin provides a signal to offset the output after load release overshoot. This network should be fine tuned during the board tuning process and is only necessary in systems with significant load release overshoot. The TRBST network allows maximum boost for low frequency load release events to minimize load release undershoot. The network time constants are set up to provide a TRBST roll off at higher frequencies where it is not needed. Cboost1 *

Rbst1 controls the time constant of the load release boost. This should be set to counter the under shoot after load release. Rbst1 + Rbst2 controls the maximum amount of boost during rapid step loading. Rbst2 is generally much larger than Rbst1. The Cboost2 * Rbst2 time constant controls the roll off frequency of the TRBST function.
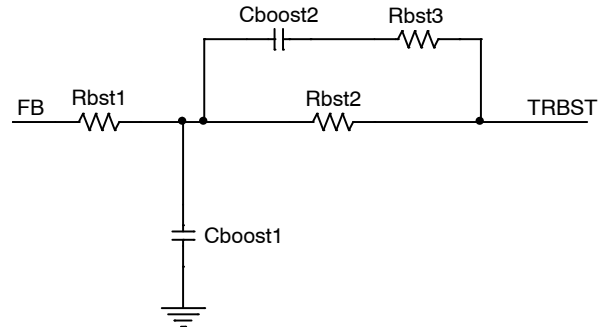

Figure 13.

PWM Comparators

During steady state operation, the duty cycle is centered on the valley of the triangle ramp waveform and both edges of the PWM signal are modulated. During a transient event the duty will increase rapidly and proportionally turning on all phases as the error amp signal increases with respect to the ramps to provide a highly linear and proportional response to the step load.

Phase Detection Sequence

During start−up, the number of operational phases and their phase relationship is determined by the internal circuitry monitoring the PWM outputs and SPHP/SPHN pin connections.

The Aux rail can be disabled by pulling the VBOOTA signal to V_{CC}. This changes the SVID address scheme to allow the multiphase to be programmed to any SVID Address odd or even. See the register resistor programming table.

Table 6. CORE RAIL SINGLE PHASE OR MULTIPHASE SETTINGS

SPHP (Pin 41)	SPHN (Pin 40)	Status
VCC	GND	Core rail single phase setting
GND	GND	Core rail multi−phase setting
GND	VCC	Core rail multi−phase setting
VCC	VCC	Core rail multi−phase setting

NOTE: SPHP/SPHN can't be floated.

Table 7. PHASE COUNT TABLE

Number of Phases		Notes:
3+1	PWM2 connected, VbootA programmed	Refer to core rail single/multi phase table for SPHP/SPHN connections
2+1	PWM2 tied to VCC, VbootA programmed	Refer to core rail single/multi phase table for SPHP/SPHN connections
3+0	PWM2 connected, VbootA tied to VCC	Refer to core rail single/multi phase table for SPHP/SPHN connections
2+0	PWM2 tied to VCC, VbootA tied to VCC	Refer to core rail single/multi phase table for SPHP/SPHN connections
1+1	PWM2 floated or connected to VCC, VbootA programmed	SPHP = VCC, SPHN = GND

Table 8. 2+1 UNUSED PIN CONNECTION TABLE

Unused Pin	Connect to
PWM2	VCC
CSN2	GND or VCC
CSP2	Same as CSN2

Table 9. 3+0 UNUSED PIN CONNECTION TABLE

Unused Pin	Connect to
VBOOTA	VCC
VSPA	GND
VSNA	GND
DIFFOUTA	float
FBA	COMPA
COMPA	FBA
TRBSTA	float
CSPA	GND
CSNA	GND
CSCOMPA	CSSUMA
CSSUMA	CSCOMPA
DROOPA	GND or CSCOMPA
ILIMA	float
IOUTA	GND
TSENSEA	GND
PWMA	float

Table 10. 2+0 UNUSED PIN CONNECTION TABLE

Unused Pin	Connect to
PWM2	VCC
CSN2	GND or VCC
CSP2	Same as CSN2
VBOOTA	VCC
VSPA	GND
VSNA	GND
DIFFOUTA	float
FBA	COMPA
COMPA	FBA
TRBSTA	float
CSPA	GND
CSNA	GND
CSCOMPA	CSSUMA
CSSUMA	CSCOMPA
DROOPA	GND or CSCOMPA
ILIMA	float
IOUTA	GND
TSENSEA	GND
PWMA	float

Table 11. 1+1 UNUSED PIN CONNECTION TABLE

Unused Pin	Connect to
PWM2	VCC
CSN2	GND or VCC
CSP2	Same as CSN2
CSN3	GND or VCC
CSP3	Same as CSN3

PROTECTION FEATURES

Input Under Voltage Protection

NCP6133 monitors the 5 V V_{CC} supply and the VRMP pin for under voltage protection. The gate driver monitors both the gate driver V_{CC} and the BST voltage (12 V drivers only). When the voltage on the gate driver is insufficient it will pull DRVON low and notify the controller the power is not ready. The gate driver will hold DRVON low for a minimum period of time to allow the controller to restart its start−up sequence. In this case the PWM is set back to the MID state and soft−start would begin again. See the figure below.
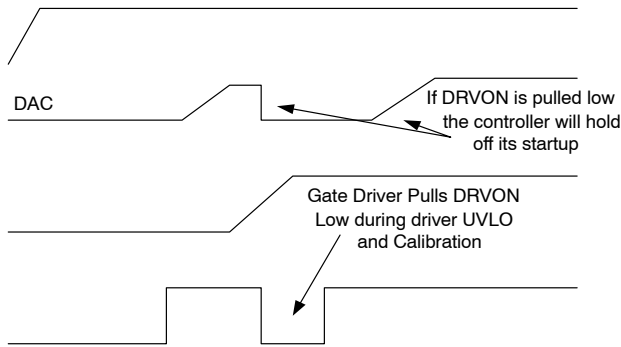

Figure 14. Gate Driver UVLO Restart

Soft−Start

Soft−start is implemented internally. A digital counter steps the DAC up from zero to the target voltage based on the predetermined slew rate in the spec table. For NCP6133, the PWM signals will start out open with a test current to collect data on phase count and for setting internal registers. After the configuration data is collected the controller enables and sets the PWM signal to the 2.0 V MID state to indicate that the drivers should be in diode mode. DRVON will then be asserted and the COMP pin released to begin soft−start. The DAC will ramp from Zero to the target DAC codes and the PWM outputs will begin to fire. Each phase will move out of the MID state when the first PWM pulse is produced preventing the discharge of a pre−charged output.
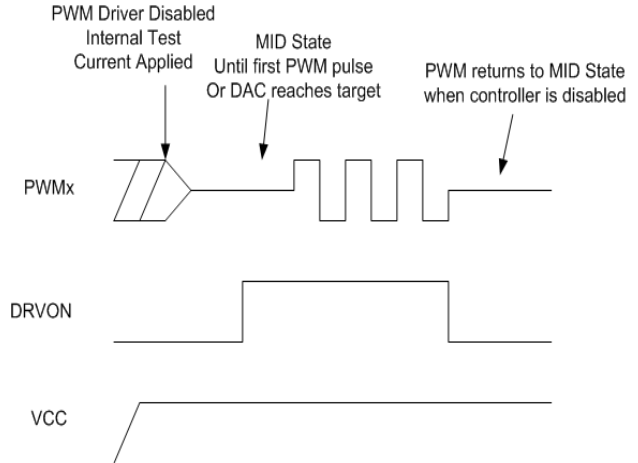

Figure 15. Soft−Start Sequence

Over Current Latch−Off Protection

During normal operation a programmable total current limit is provided that scales with the phase count during power saving operation. The level of total current limit is set with the resistor from the ILIM pin to CSCOMP. The current through the external resistor connected between ILIM and CSCOMP is then compared to the internal current of 10 μA and 15 μA. If the current into the ILIM pin exceeds the 10 A level an internal latch−off counter starts. The controller shuts down if the fault is not removed after 50 μs. If the current into the pin exceeds 15 μA the controller will shut down immediately. To recover from an OCP fault the EN pin must be cycled low.

The over−current limit is programmed by a resistor on the ILIM pin. The resistor value can be calculated by the following equation:

$$R_{ILIM} = \frac{V_{CSCOMP} - V_{CSREF}}{10\ \mu A} \qquad \text{(eq. 11)}$$

Under Voltage Monitor

The output voltage is monitored at the output of the differential amplifier for UVLO. If the output falls more than 300 mV below the DAC−DROOP voltage the UVLO comparator will trip sending the VR_RDY signal low.

Over Voltage Protection

During normal operation the output voltage is monitored at the differential inputs VSP and VSN. If the output voltage exceeds the DAC voltage by approximately 300 mV, PWMs will be forced low until the voltage drops below the OVP threshold. After the first OVP trip the DAC will ramp down to zero to avoid a negative output voltage spike during shutdown. When the DAC gets to zero the PWMs will be forced low and the DRVON will remain high. To reset the part the Enable pin must be cycled low. During soft−start and DVID, the above OVP is disabled. This allows the controller to start up without false triggering the OVP. Meanwhile, there is a second OVP protection which is always enabled. The second OVP monitors CSREF(A) pin voltage with a protection threshold of 2.3 V.

Figure 16. OVP Threshold Behavior

Layout Notes

The NCP6133 has differential voltage and current monitoring. This improves signal integrity and reduces noise issues related to layout for easy design use. To insure proper function there are some general rules to follow. Always place the inductor current sense RC filters as close to the CSN and CSP pins on the controller as possible. Place the V_{CC} decoupling cap as close as possible to the controller VCC pin, the resistor in series should always be no higher than 2.2 Ω to avoid large voltage drop. The high frequency filter cap on CSREF and the 10 Ω CSREF resistors should be placed close to the controller. The small high feed back cap from COMP to FB should be as close to the controller as possible. Please minimize the capacitance to ground of the FB traces by keeping them short. The filter cap from CSCOMP to CSREF should also be close to the controller.

ORDERING INFORMATION

Device	Package	Shipping[†]
NCP6133MNTWG	QFN52 − Single Row (Pb−Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NCP6133

PACKAGE DIMENSIONS

QFN52 6x6, 0.4P
CASE 485BE
ISSUE B

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TIP
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS

DETAIL B
ALTERNATE CONSTRUCTION

EXPOSED Cu   MOLD CMPD

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
D	6.00 BSC	
D2	4.60	4.80
E	6.00 BSC	
E2	4.60	4.80
e	0.40 BSC	
K	0.30 REF	
L	0.25	0.45
L1	0.00	0.15
L2	0.15 REF	

TOP VIEW

PIN ONE LOCATION

0.10 C
0.10 C

SIDE VIEW

DETAIL B
(A3)
A1
NOTE 4
0.10 C
0.08 C
C SEATING PLANE

BOTTOM VIEW

DETAIL C
DETAIL A
14
27
52
40
1
D2
K
E2
52X L
52X b
e

0.07 C A B
0.05 C   NOTE 3

DETAIL C
8 PLACES
L2   L2

SOLDERING FOOTPRINT*

6.40
4.80
4.80
6.40
52X 0.63
0.40 PITCH
52X 0.25
PKG OUTLINE
DETAIL D

DETAIL D
8 PLACES
0.11   0.49

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NCP6133/D